■

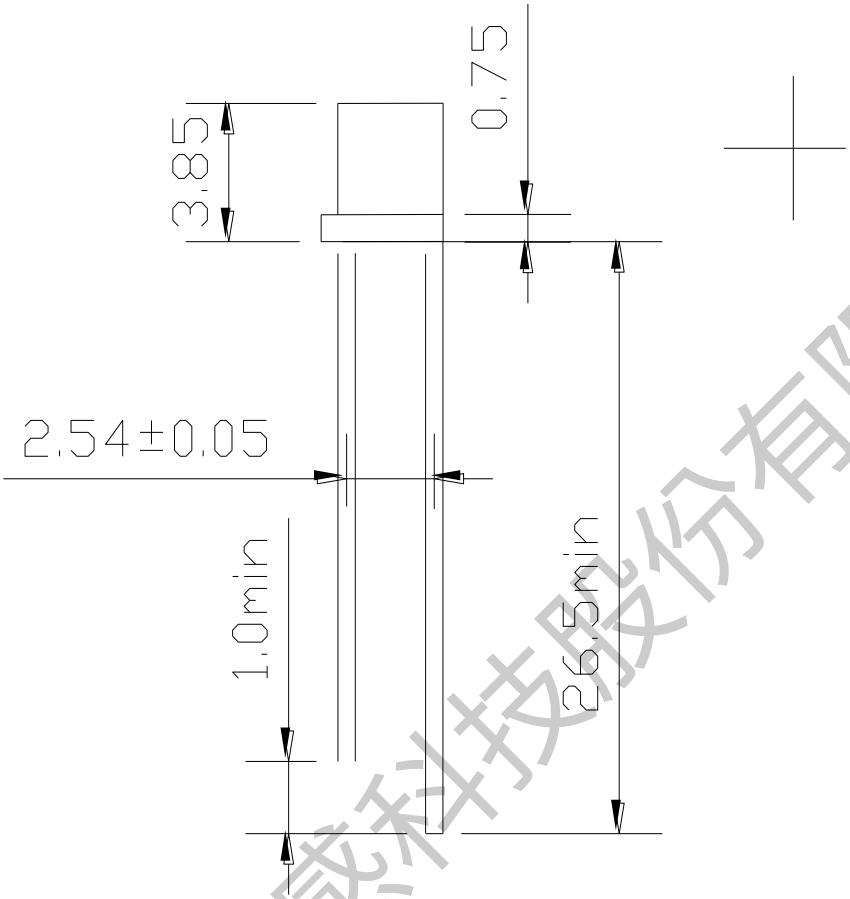
Product function

1. (CdS) ROHS
Replace Photoresistors(Cds),RoHS Compliance/Pb-free/Cd-free.
2. LCD
adjust b8 66e[kgs(rouree[d) lig3(-2(h)t 8(b8 66e[µ2(h)t3((Co)-3b8 66e[ic 66e[l(liy3(c),L(to)-3(4(,mob3(m

2.

2.

■ Product Dimensions

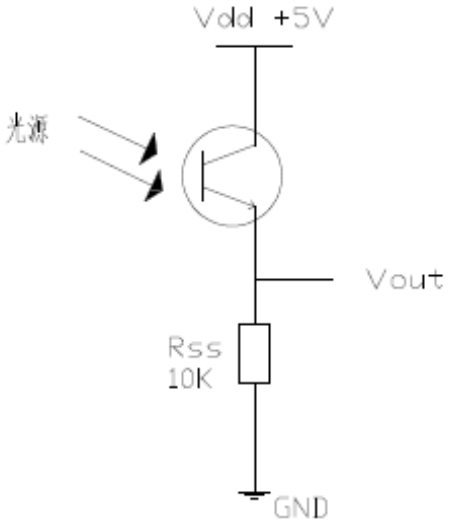


Note

1. **Long pin- Collector Short pin- Emitter**
2. mm , ±0.15mm
   Unit: mm± 0.15mm
3. **The appearance color of colloid shall be subject to the sample**
4. **1.0mm**
   Protruded resin under the base is 1.0mm maxium.

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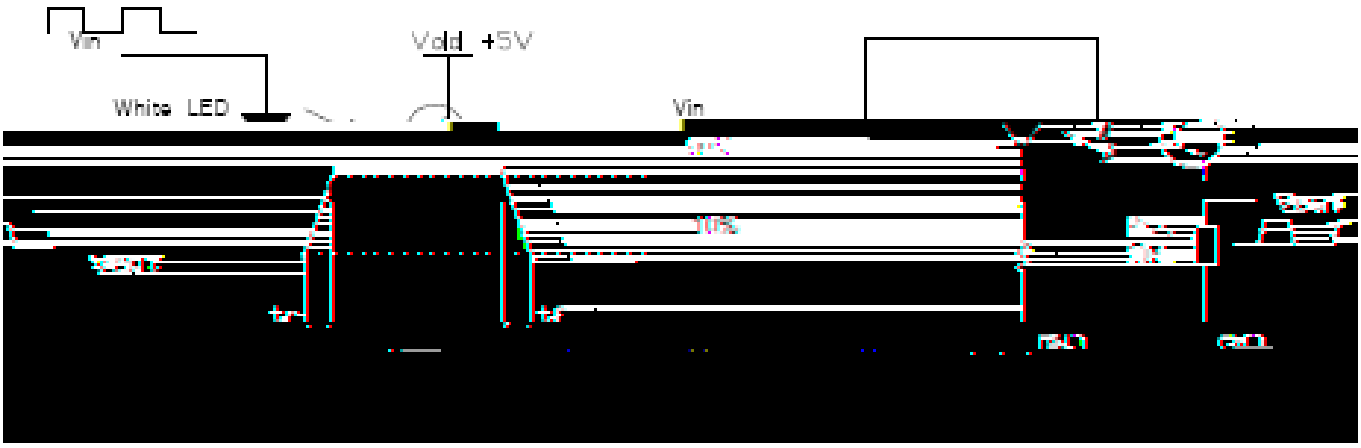
■ Test schematic



Photocurrent =V_{out}/ R_{SS}

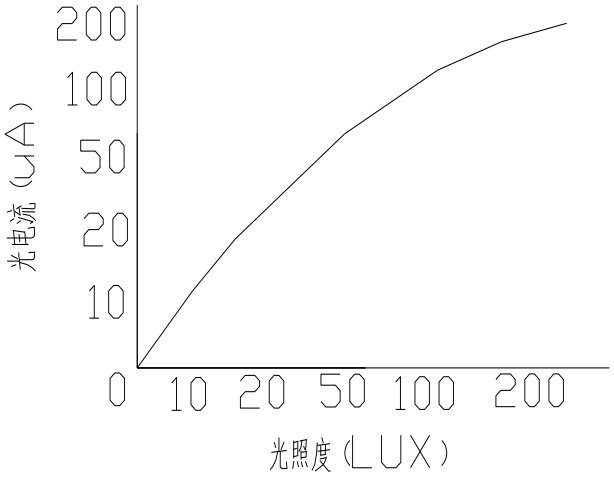
* R_{SS} .

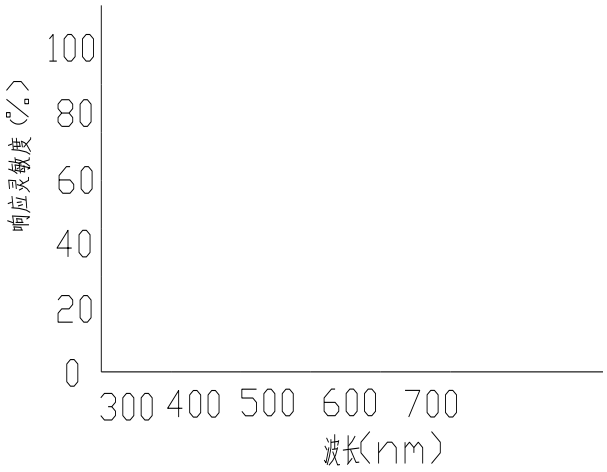
High stable resistance is recommended for RSS

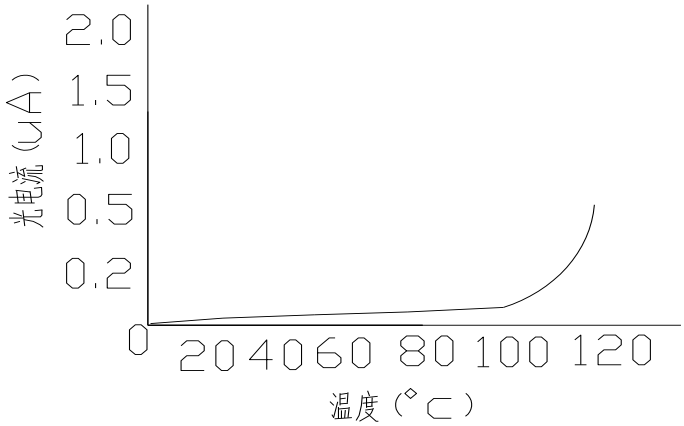


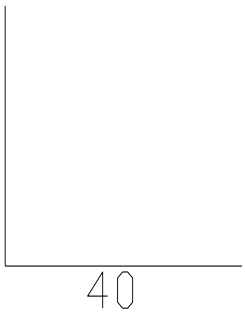
MeasureM1 0 00 g0thefitc8(is inge)- t(is imTf1e1 251.929993 177

■ Typical photoelectric characteristics curves









■ Reliability Test

Test Parameter	Reference Criterion	Test Condition	Time	Quantity	/ Ac/RE
Resistance to Solder Heat	JESD22-B106	260 ±5	10sec	30PCS	0/1
Thermal Cycle	JESD22-A104	110 (15min) 5min - 15 (15min)	50 cycles	30PCS	0/1
Thermal Shock	JESD22-A104	120 (30min) - 45 (30min)	50 cycles	30PCS	0/1
High Temprature storage	JESD22-A103	100	1000H	30PCS	0/1
Low Temperature storage	JESD22-A119	- 40	390.2900 0.4800 69.2640 ref*QEMC/P A1		

■ **Recommended Soldering Conditions**

Mode		Condition
Manually Soldering	Soldering Iron Temperature	340 60 Max340 (power:60Wmax)
	Soldering Time	3 ≤ 3 seonds
	Soldering Position	1.5mm 1.5mm Min.(Form soldering joint to colloid)
Wave Soldering	Preheat	110 80 110 Max.80 sec.Max.
	Temperature	260 ≤ 260
	Soldering Time	5 ≤ 5 seonds
Solder pot Soldering	Preheat	100 60 100 Max.60 sec.Max
	Preheat Temperature	260 ≤ 260
	Soldering Time	5 ≤ 5 seonds
	Soldering Posiion	1.5mm 1.5mm(Form soldering joint to colloid

Notes

Careless operation in the welding process will cause product damage. During the welding process, any pressure on the product bracket or package part shall be avoided.

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■ Precautions

1. 0 +30°C